

X-ray analysis: Mauro Sardela Jr. Advanced Materials Characterization Workshop AMC2019 University of Illinois at Urbana-Champaign







X-ray radiation mostly used in lab instruments: *Cu* radiation • *Cu* Kα: λ= 0.15418 nm (8.05 keV, conventional resolution)

• Cu K α 1: (λ = 0.15056 nm (high resolution)

X-ray interactions with matter









M. von Laue 1879-1960 X-rays from crystals, 1912.









Bragg's law and Ewald's sphere





Two-dimensional XRD:



20



2θ-ω scan: Probes *d*-spacing variation Along *q* Phases id, composition, lattice constants Grain sizes, texture, strain/stress



2theta/omega scan







2theta/omega scan







Detector 2theta/omega scan

Peak position: identification, structure, lattice parameter Peak width: crystallite size, strain, defects Peak area or height ratio: preferred orientation Peak tails: Diffuse scattering, point defects Background: amorphous contents





0

X-ray tube

 $\mathbf{\Omega}$

1000-

Intensity(Counts)

⁽¹¹¹⁾ Si(111)

What type of radiation?

1

- Cu, Cr, Mo, Ag, W...
- Penetration depth
 - 2θ peak positions

0

a

2Line or point focus?Peak resolution and shape

Sample irradiated area

0

a

3

What type of monochromator?

• Filter, x-ray mirror, crystal monochromator

0

a

• White radiation, $K\alpha 1 + K\alpha 2$, $K\alpha 1$

X-ray beam footprint on the sample?

a

4

• Shape, size

0

• Depth

Horizontal, vertical goniometer?

5

Sample stage? 3,4 circle?

0

0

What type of detector?

0

a

6

- Resolution
- Point, Line, Area



Bragg-Brentano focusing configuration





2-theta (degrees), Cu K-alpha radiation

XRD powder pattern



Peak fit and shape analysis



ntensity (sqrt counts)

2-theta (degrees), Cu K-alpha radiation





	Hits	Formula	FOM	PDF	RIR	Space group
V	Calcite	CaCO ₃	1.1	04-012-0489	3.45	R-3c(167)
	Dolomite	Ca _{1.07} Mg _{0.93} (CO ₃) ₂	15.0	04-011-9830	2.51	R-3(148)



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Quant: RIR reference intensity ratio

Ratio of crystalline phases

Ratio of peak areas corrected by RIR of each phase

RIR ~ I / I _{corundum}





 $w_i, b_i, K_i, Y_{l,i}$ weight, background, scale factor and peak shape function



Refinement of parameters: Background Sample displacement, transparency and zero-shift correction Peak shape function Unit cell dimensions Preferred orientation Scale factors Atom positions in the structure Atomic displacement parameters





1104

(202)

(1 3)

40

(110)

30

012)

20

Intensity (sqrt counts)

 Calcite:
 80.7 w%

 Dolomite:
 22.2 w%

 Amorphous:
 17.1 w%

Crystallite size:Calcite:56.8 nmDolomite:35.6 nm

80

90

100

110

2-theta (degrees), Cu K-alpha radiation

70

60

(122)

50



2-theta (degrees), Cu K-alpha radiation



2-theta (degrees), Cu K-alpha radiation


Crystallite size analysis



Crystallite size analysis



Peak shape analysis



Correction for instrument resolution



Potential artifacts in size determination

For this calculation assume: Instrument resolution ~ 0.15° •Cu radiation

$2\theta = 40^{\circ}$ Measured peak width	Size, nm D = 1 (Lorentzian) $\beta =$ $\beta_{meas} - \beta_{instr}$	Size, nm D = 1.5 $\beta^{1.5} =$ $(\beta_{meas})^{1.5} - (\beta_{instr})^{1.5}$	Size, nm D = 2 (Gaussian) $\beta^2 =$ $(\beta_{meas})^2 - (\beta_{instr})^2$	
0.30°	56.4	38.0	32.6	48%difference for
0.50°	24.2	19.2	17.7	narrow peaks (large sizes)
0.75°	14.1	12.0	11.5	
1.00°	10.1	8.8	8.6	Smaller
1.50°	6.3	5.8	5.7	difference (~ 10%) for
2.00°	4.6	4.3	4.2	broad peaks

He et al, Adv in X-ray Analysis 37, vol 46 (2003)









Non uniform rings (texture)



Spotty rings (large grain size) Pyroxene: increasing grain sizes Collected by *Curiosity* rover, Gale crater, Mars



Bramble et al, 45th Lunar and Planetary Science Conference (2014)

Strain effects in diffraction lines



Size and strain in peak shape analysis



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X-ray parallel beam methods





Rough, irregular surfaces

Film / Substrate systems



Glancing / grazing angle applications. Phase, stress gradients (depth profiles)



Parallel beam configuration





After Shin et al, TSF (2002)

Thin film analysis walkthrough:



Peak shape analysis: TaN(002) rocking curve omega scans



Glancing incidence x-ray diffraction (GI-XRD)





: conventional Bragg-Brentano configuration $2\theta - \omega$ scans probe only grains aligned parallel to the surface

+ : parallel-beam **glancing incidence** configuration 2θ scans probe grains in <u>all</u> directions

X-ray penetration depth vs. angle of incidence



Regular 2 θ - ω scan vs. glancing incidence 2 θ scan



	Regular 2 θ – ω scan	Glancing incidence 2θ scan
Grain orientations	Directions ⊥ to surface	Various directions
Depth resolution	Constant, many mm	 From few nm to mm <u>Depth profiling possible by</u> varying angle of incidence Sensitive to surface Ideal for ultra-thin layers
Best configuration	Bragg Brentano Parallel beam	Parallel beam (less sensitive to sample displacement)

Glancing incidence x-ray analysis

Example: Poly-Si ga





Determination of preferred orientation

Method	Measurement	Principle	Results
Lotgering factor (L _{hkl})	2θ-ω scans	Compare I_{peak} or A_{peak} with expected values from random samples (PDF)	L _{hkl} as measure of texture strength
March- Dollase (MD)	2θ-ω scans	Use $I_{peak} \text{ or } A_{peak} \text{ with MD}$ formalism	% of grains that are more oriented along a specific direction
Rocking curve	ω scans	Measure FWHM from ω scan for a particular (<i>hkl</i>)	FWHM decreases with stronger texture
Pole figure	ϕ scans at various tilts ψ	Pole plots of intensities from a particular (<i>hkl</i>)	Texture distribution for a single (<i>hkl</i>)
Orientation Distribution Function (ODF)	Pole figures from various (<i>hkl</i>) 's	Calculate ODF from various pole figures with background and defocussing correction	% of grain orientation distribution in all directions (Euller angles).

Pole figure measurement



Pole figures



Basics of pole figure analysis



Cu (111) pole figure



X-ray pole figure analysis of textured materials



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Data: Sardela, UIUC

X-ray pole figure analysis of textured materials



Data: Sardela, UIUC

High resolution XRD methods



Single crystals:

Accurate measurements of **a**, **b**, **c**, α , β , γ

Detailed peak shapes: defects, mosaicity.



Film / substrate epitaxial systems:

Measure small variations Δa , Δc ,... (~ 10⁻⁵).

Measure layer tilts $\Delta \phi$, ...

Detailed peak shapes: defects, strain, mosaicity.







Multiple rlp's Relative position Orientation Shape

Instrument resolution in reciprocal space



Instrument resolution in reciprocal space



Instrument resolution in reciprocal space



Instrumentation: high resolution configuration



High resolution x-ray analysis

- Lattice distortions within 10⁻⁵.
- Rocking curve analysis.
- Film thickness.
- Strain relaxation and lattice parameter measurements.
- Alloy composition and superlattice periods.
- Interface smearing in heterostructures (dynamical simulation).





High resolution x-ray analysis



High resolution 2θ/θ scan near GaAs(004)



a_{substrate}

Data: Sardela 69 Sample: Highland, Cahill, Coleman et at, UIUC

High resolution x-ray analysis

Example: strained In_xGa_{1-x}As on GaAs (001) substrate

Lattice structure

 $a_{// \text{ film}} = a_{\text{substrate}}$ $a_{\perp \text{ film}}$ $a_{\text{substrate}}$ $a_{\text{substrate}}$ $a_{\text{substrate}}$

a_{substrate}

High resolution 2θ/θ scan near GaAs(004) and dynamical scattering simulation



Data: Sardela Sample: Highland, Cahiii, Coiema



Reciprocal space mapping

Direct space:



Reciprocal space mapping










The "shape" of the reciprocal lattice point



X-ray reflectivity



Liquids:



Multilayered systems:



Near surface and interface information on:

Density

Porosity

Roughness

Thickness in films (ultra thin to thick)

Amorphous or crystalline materials

X-ray reflectivity



X-ray reflectivity analysis of thin films



X-ray reflectivity data fitting in ultra-thin films



X-ray reflectivity data fitting

Simulation using Parrat's formalism and generic algorithm fitting



X-ray reflectivity: summary

- * Non destructive method
- * Applicable to whole wafers (wafer mapping option)
- * Fast method (in most cases)
- * Do not depend on crystalline quality of the films (can also be used in amorphous layers).

Quantification of:

- * Layer thickness in thin films and superlattices: 1 nm ~ 1 μ m (± 0.5-1%).
- * Layer density and porosity (± 1-2%).
- * Interface roughness: 0.1 10 nm (model dependent; reproducibility ~ 3%).
- * Layer density gradients (variations > 2%).
- * Interface roughness correlation in superlattices and multilayers.

Alternative techniques:

- * Thickness: optical methods (TEM, SEM) poor contrast issues.
- * Density: RBS (issues for ultra thin layers).
- * Interface roughness: AFM (surface only not buried interfaces).

Small angles... large things...



SAXS instrument



Small angle x-ray scattering





SAXS and GI-SAXS



Sample holder for powders



0.8



Temperature control stage for capillaries



-20°C up to 120°C







SAXS applications:

Analysis:

- Crystalline structure
- Degree of crystallinity and orientation
- Particle shape, size, distribution
- Radius of gyration
 Guinier plot *Ln I(q) vs. q²*
- Folded, partially or unfolded proteins
 Kratky plot *I(q)*q² vs. q*
- Distance distribution function *p(r)*

<u>Materials</u>:

- Nanoparticles
- Membranes
- Lipids
- Polymers
- Proteins
- Solutions
- Nanocomposites
- Polymers
- Thin films ...

Residual stress analysis methods





Residual stress?

How much? (MPa – GPa)

Type?

Direction (s)?

Stress gradients?



Hooke's law Stress tensor Elastic properties (E, v)

X-ray analysis of residual stress





Data: Sangid et al, UIUC

- Quantification of residual stress.
- Compressive (-) and tensile (+) stress.
- Crystallographic orientation of stress.
- Sin² ψ method. Linear for rotationally symmetric biaxial stress where the only non-zero components are $\sigma_{11} = \sigma_{22} = \sigma_{11}$
- ψ and ω scan methods.
- Glancing angle method (texture).
- Determination of stress tensor.
- Requires crystallinity (no amorphous). ⁹³



Analytical lateral resolution



Analytical lateral resolution



Analytical lateral resolution

Typical analysis depth for common analytical techniques



www.eag.com

X-ray analysis summary



(-) Localized info (below 100 μm) Defects identification and quantification Direct imaging